

In the Abstract:

ABSTRACT OF THE DISCLOSURE

~~Thin film semiconductor component and production method for said component~~

~~The invention relates to a~~ A semiconductor component having a thin-film semiconductor body (2) arranged on a germanium-containing carrier (4). A method for producing such a semiconductor component includes producing a semiconductor component having a thin-film conductor body arranged on a carrier, having the steps of growing the thin-film semiconductor body on a substrate, applying the carrier to a side of the thin-film semiconductor body that is remote from the substrate, and stripping the thin-film semiconductor body from the substrate, wherein the carrier contains germanium. ~~is furthermore described.~~

~~Figure 1~~